

S/N	Item	Capability Description	
		Normal	Update
1	Layers count	2-12层 2-12 layers	14-16层 14-16 layers
2	Finished Board Thickness	16~128 mil (0.4mm~3.2mm)	128~134 mil (3.2mm~4.0mm)
3	Max. panel size	24× 24.5" ( 622mm × 610mm )	32× 15" ( 820mm ×390mm )
4	Laminate Materials	FR-4 CEM-3 Mid Tg High Tg High CTI Halogen Free Lead free compatible	High Frequency Teflon
5	Finished board Thickness tolerance	< 1.0mm ±0.10mm (±4mil) 1.0~1.6mm ±0.15mm (6mil)	< 1.0mm ±0.075mm (±3mil) 1.0~1.6mm ±0.10mm (4mil)
6	Min. Inner thin core thickness	3mil (0.075mm)	/
7	Min. Inner Line Width/Spacing	3.5/3.5mil(0.089/0.089mm)	3.0/3.0mil(0.075/0.075mm)
8	Min. outer Line width/spacing	4.0/4.0mil(0.1/0.1mm)	3.0/3.0mil(0.075/0.075mm)
9	Layer-to-layer registration tolerance	± 3mil (± 0.075mm )	± 2mil (± 0.05mm )
10	Copper foil thickness	12um,18um, 35um, 70 um, 105 ,140um(1/3oz-4oz)	175-210um (5-6oz)
11	Min. finished hole size	0.20mm	0.15mm
12	Min. drilling bit size	0.25mm	0.2mm
13	Max. drilling bit size	6.5mm	/
14	Finished hole size tolerance (PTH)	± 0.075mm(±3mil)	± 0.05mm(±2mil)
15	Finished hole size tolerance (NPTH)	± 0.05mm (±2mil)	/
16	Drilling precision tolerance (Compared with CAD data)	± 0.075mm (±3mil)	± 0.05mm (±2mil)
17	PTH hole copper thickness	20-30um	30-35um
18	Max. aspect ratio	≤8:1	10:1
19	Impedance control	±10%	/
20	Min SMT PAD pitch & precision tolerance	0.4 ±0.1mm (16 ± 4mil)	0.4 ±0.075mm (16 ±3mil)
21	Min. solder mask opening	0.05mm (2mil)	0.0375mm (1.5mil)
22	Min. solder mask dam	0.076mm (3mil)	0.063mm (2.5mil)
23	Surface Finish	OSP, Peelable Solder Mask, carbon ink, HASL (lead free),.ENIG,I-Ag,I-Tin	OSP, Peelable Solder Mask, carbon ink, HASL (lead free),.ENIG,I-Ag,I-Tin
24	OSP	F2: 0.2-0.3um	/
25	V-Cut angle	30° 、 45° 、 60°	/
26	Min. V-cut board thickness	0.3mm	/
27	Profiling mode	Routing & Punching	/
28	Dimensional tolerance	± 0.10mm (4mil)	/
29	E-Test voltage	250 ± 5V	/
30	Max. E/T insulation resistance	100 MΩ	/
31	Min.E/T conductive resistance	20MΩ	/